NTNS3190NZ

Advance Information **Small Signal MOSFET** 20 V, 230 mA, Single N-Channel, 0.62 x 0.62 x 0.4 mm XLLGA3 Package

Features

- Single N-Channel MOSFET
- Ultra Small and Thin Package (0.62 x 0.62 x 0.4 mm)
- Low R_{DS(on)} Solution in 0.62 x 0.62 mm Package
- 1.5 V Gate Voltage Rating
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Small Signal Load Switch
- Analog Switch
- High Speed Interfacing
- Optimized for Power Management in Ultra Portable Products

MAXIMUM RATINGS (T_J = 25° C unless otherwise stated)

Parameter		Symbol	Value	Units		
Drain-to-Source Voltage			V _{DSS}	20	V	
Gate-to-Source Voltage			V _{GS}	±8.0	V	
Continuous Drain	Steady State	$T_A = 25^{\circ}C$	۱ _D	230	mA	
		$T_A = 85^{\circ}C$		165		
	t ≤ 5 s	$T_A = 25^{\circ}C$		296		
Power Dissipa- tion (Note 1)	Steady State	$T_A = 25^{\circ}C$	P _D	125	mW	
	t ≤ 5 s	T _A = 25°C		208		
Pulsed Drain Current $t_p = 10 \ \mu s$		I _{DM}	688	mA		
Operating Junction and Storage Temperature			T _J , T _{STG}	-55 to 150	°C	
Source Current (Body Diode) (Note 2)			۱ _S	125	mA	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Units
Junction-to-Ambient - Steady State (Note 1)	$R_{ extsf{ heta}JA}$	1000	°C/W
Junction-to-Ambient – t \leq 5 s (Note 1)	R _{θJA}	600	

1. Surface Mounted on FR4 Board using the minimum recommended pad size, (or 2 mm²), 1 oz Cu.

2. Pulse Test: pulse width \leq 300 μ s, duty cycle \leq 2%.

This document contains information on a new product. Specifications and information herein are subject to change without notice.



ON Semiconductor®

http://onsemi.com

MOSFET				
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX		
20 V	1.4 Ω @ 4.5 V			
	1.9 Ω @ 2.5 V	230 mA		
	2.2 Ω @ 1.8 V	200 11/1		
	4.3 Ω @ 1.5 V			



MARKING DIAGRAM



X = Specific Device Code M = Date Code

M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]			
NTNS3190NZT5G	XLLGA3 (Pb-Free)	8000 / Tape & Reel			

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NTNS3190NZ

ELECTRICAL CHARACTERISTICS (T₁ = 25°C unless otherwise specified)

		•	,				
Parameter	Symbol	Test Condition		Min	Тур	Max	Units
OFF CHARACTERISTICS	-				-		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_{D} = 250 μ A		20			V
Zero Gate Voltage Drain Current	I _{DSS}					1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 8.0 \text{ V}$				±2.0	μA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 250 \ \mu A$		0.4		1.0	V
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 100 \text{ mA}$ $V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 50 \text{ mA}$ $V_{GS} = 1.8 \text{ V}, \text{ I}_{D} = 20 \text{ mA}$ $V_{GS} = 1.5 \text{ V}, \text{ I}_{D} = 10 \text{ mA}$			0.75	1.4	Ω
					1.0	1.9	
					1.3	2.2	
					1.6	4.3	
Source-Drain Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 10 mA			0.7	1.0	V
CHARGES, CAPACITANCES & GATE	RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 15 V			15.8		pF
Output Capacitance	C _{OSS}				4.6		
Reverse Transfer Capacitance	C _{RSS}				3.3		
SWITCHING CHARACTERISTICS, VG	i S = 4.5 V (Note 3)			-	-	-	
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 4.5 V, V_{DD} = 15 V, I _D = 200 mA, R _G = 2 Ω			20		ns
Rise Time	tr				45		
Turn-Off Delay Time	taiorry				240		

3. Switching characteristics are independent of operating junction temperatures.

t_{d(OFF)}

t_f

Turn-Off Delay Time

Fall Time

TYPICAL CHARACTERISTICS

140



NTNS3190NZ

PACKAGE DIMENSIONS

XLLGA3, 0.62x0.62, 0.35P CASE 713AA ISSUE A









NOTES:

RECOMMENDED SOLDER FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and use registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death agsociated with such unintended or unauthorized use payers that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunit//Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below :

614233C 648584F IRFD120 JANTX2N5237 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L SBVS138LT1G 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B